



M.2 Connector, B Key, H=5.8mm, 0.5 Pitch, GF

123A-58B01

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M.2 connector, also known as the Next Generation Form Factor (NGFF) is originally designed for the ultra-thin products. Its compact size could save over 20% of PCB design space compare with mini PCIe connector. M.2 connector applies to high-speed data transmission that supports PCI Express 3.0, SATA 3.0 and USB 3.0.

MAIN FEATURES



Miniature in size:

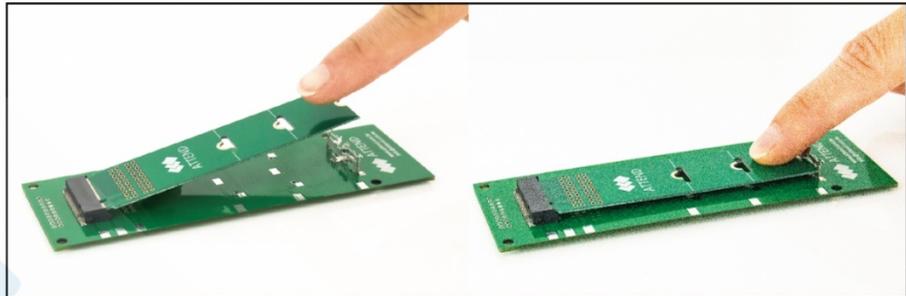
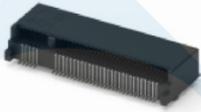
Compared with Mini PCI Express, M.2 saves 25% in heights and 55% in which sufficiently save the space of the PCB layout.

There are two key dimension need to check.

- Dim. A : The heights are between min- 2.1mm to max- 8.5mm.
- Dim. B : For double-sided modules, this height is also important to keep in mind.

"Click"

Quick Click



ATTEND "Click" Solution allows you to assemble the card without screw driver less than 1 second.

Quick Click		
<p>Less than 1 second for assembly.</p> <p>1 2</p>	<p>No screw driver needed.</p>	<p>Easily disassembly.</p> <p>1 2</p>

APPLICATION:

- SSD Module
- Wi-Fi Module
- NAS
- Tablets
- Gaming
- Servers



P/N	123A-21A00, H=2.1mm 123A-30A00, H=3.0mm 123A-40A00, H=4.0mm 123A-85AA0, H=8.5mm	123A-21B00, H=2.1mm 123A-30B00, H=3.0mm 123A-40B00, H=4.0mm 123A-58B01, H=5.8mm 123A-85BA0, H=8.5mm	123A-21E00, H=2.1mm 123A-30E00, H=3.0mm 123A-40E00, H=4.0mm 123A-58E01, H=5.8mm 123A-85EA0, H=8.5mm	123A-21M00, H=2.1mm 123A-30M00, H=3.0mm 123A-40M00, H=4.0mm 123A-58M01, H=5.8mm 123A-85MA0, H=8.5mm
Type	A Key 	B Key 	E Key 	M Key 
Dim A. Height	2.1mm, 3.0mm, 4.0mm, 8.5mm	2.1mm, 3.0mm, 4.0mm, 5.8mm, 8.5mm	2.1mm, 3.0mm, 4.0mm, 5.8mm, 8.5mm	2.1mm, 3.0mm, 4.0mm, 5.8mm, 8.5mm
Dim B. Height	0.65mm, 1.35mm, 2.35mm, 6.6mm	0.65mm, 1.35mm, 2.35mm, 4.8mm, 6.6mm	0.65mm, 1.35mm, 2.35mm, 4.8mm, 6.6mm	0.65mm, 1.35mm, 2.35mm, 4.8mm, 6.6mm
Available Accessories <small>For H=3.0, 4.0, 5.8 mm</small>	 123A-30L1, 123A-40L1	 123A-30L1, 123A-40L1, 123A-58L1	 123A-30L1, 123A-40L1, 123A-58L1	 123A-30L1, 123A-40L1, 123A-58L1
Module Card Type	22110, 2280, 2260, 2242, 2230, 3042, 3030	22110, 2280, 2260, 2242, 2230, 3042, 3030	22110, 2280, 2260, 2242, 2230, 3042, 3030	22110, 2280, 2260, 2242, 2230, 3042, 3030
Applications	Wireless Connectivity devices including combinations of Wi-Fi,BT, HFC, and/or WiGig	SSD or WWAN + GNSS (2G GSM, GPRS, 3G, CDMA,WLAN, WWLAN, HSPA MODEM,GPS, 4G WiMAX)	Wireless Connectivity devices including combinations of Wi-Fi,BT, NFC, and/or GNSS	SSD devices and Host I/Fs supported are PCIe with up to four lanes or SATA

SPECIFICATION

ELECTRICAL

Current Rating	0.5A per pin
Voltage Rating	50VAC
Contact Resistance	55mΩ, Δ20Ω Max.
Insulation Resistance	500MΩ
Dielectric Withstanding Voltage	300VAC

MECHANICAL

Durability	60 Cycle
Mating Force	20N max.
Un-mating Force	20N max.

ENVIRONMENTAL

Operating temperature range	-40°C~+85°C
Storage temperature range	-40°C~+85°C

SOLDER ABILITY

Recommended IR Reflow(Wave Soldering) Temperature	260°C
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